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PC35H11 V0

Product Specification



Approval Sheet

PC35H11 V0
Product Specification



Product	White SMD LED
Part Number	PC35H11 V0
Issue Date	2015/10/13



Feature

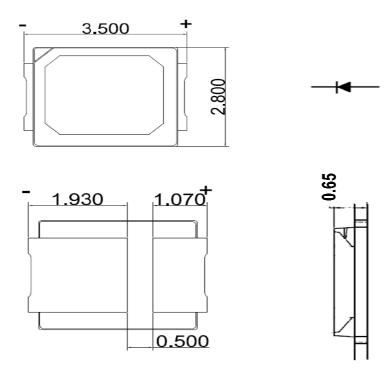
- \checkmark White SMD LED (L x W x H) of 3.5x 2.8 x 0.7 mm
- ✓ Erp Ellipse Binning
- ✓ Dice Technology : InGaN
- ✓ Qualified according to JEDEC moisture sensitivity Level 3
- ✓ Environmental friendly; RoHS compliance
- ✓ Packing: 1000 or 4000 pcs/reel

Applications

- ✓ Portable flashlight
- √ Reading lights
- ✓ Security / garden lighting
- √ General lighting
- √ Indoor and outdoor commercial lighting

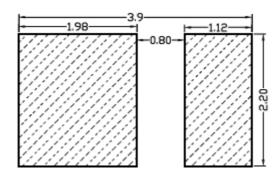


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nit: mm, Tolerance: ±0.1mm

■ Recommended Soldering Pad





Performance

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■ Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Voltage ⁽¹⁾	V _F		2.9	-	3.4	V
Color Rendering Index ⁽²⁾	Ra	1 450 50 1	80	-	-	-
View Angle	θ	$I_F = 150 \text{ mA}$	-	120	-	deg
Thermal Resistance ⁽³⁾	R _{th}		-	25	-	°C/W

- (1) The Forward Voltage tolerance is ±0.1V
- (2) The Color Rendering Index tolerance is ±2
- (3) Thermal resistance is calculated from junction to solder

■ Luminous Flux (Ta=25°C)

ССТ	Condition	Rank
2600K~3700K	1 150 m A	VM, VN, VO
3700K~7000K	$I_F = 150 \text{ mA}$	VN , VO, VP

^{*} The luminous flux tolerance is ± 7%

■ Absolute Maximum Ratings

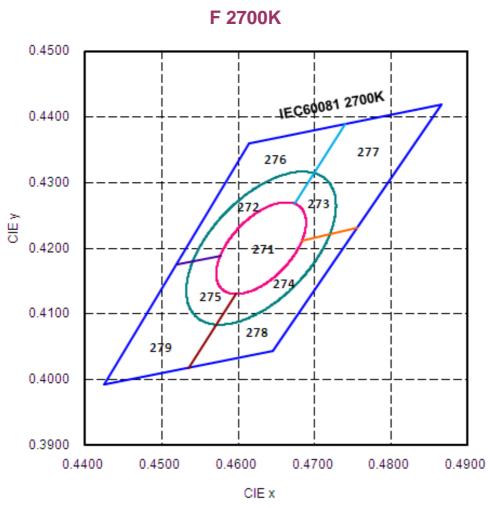
Parameter	Symbol	value	Unit
DC Forward Current ⁽¹⁾	I _F	180	mA
Power Dissipation	P_D	0.65	W
Pulse Forward Current (2)	I _{FP}	360	mA
Storage Temperature	T _{stg}	-40 ~ 100	°C
Operating Temperature	T_{opr}	-40 ~ 85	°C
Junction Temperature	T_J	120	°C
Assembly Temperature		260 (5 sec)	°C

- (1) Proper current rating must be observed to maintain junction temperature below maximum at all time
- (2) IFP Condition: Duty 1/10, Pulse within 10msec



ERP Binning

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ССТ	Color Space	Target Center	Major Axis,	Minor Axis,	Ellipse Rotation
		Point (cx, cy)	а	b	Angle
2720K	Single 3-step	(0.463, 0.420)	0.00810	0.00420	53.70°
	MacAdam ellipse				
2720K	Single 5-step	(0.463, 0.420)	0.01350	0.00700	53.70°
	MacAdam ellipse				



■ Bin code definition

V _F Rank	Luminous Flux Rank	CIE Rank
2	VO	275

V _F Rank	Condition	Min.	Max.
1		2.9	3.0
2		3.0	3.1
3	$I_F = 150 \text{ mA}$	3.1	3.2
4		3.2	3.3
5		3.3	3.4
Luminous Flux Rank	Condition	Min.	Max.
VM		55	60
VN	1 450 m A	60	66
VO	$I_F = 150 \text{ mA}$	66	72
VP		72	78

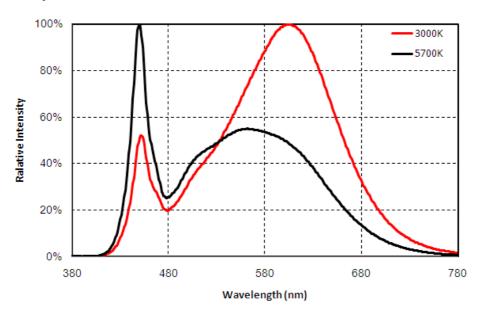
Note:

- (1) The luminous flux tolerance is $\pm 7\%$
- (2) The Forward Voltage tolerance is ±0.1V

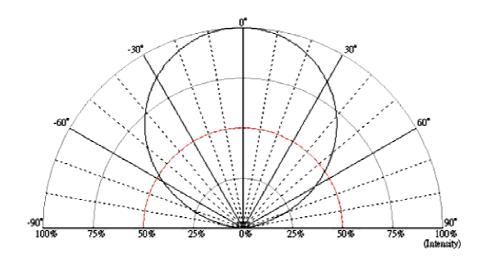


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Spectrum

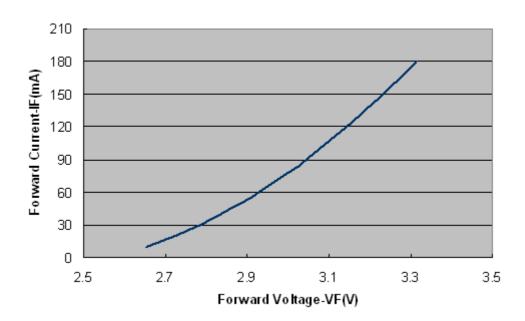


Radiation Pattern

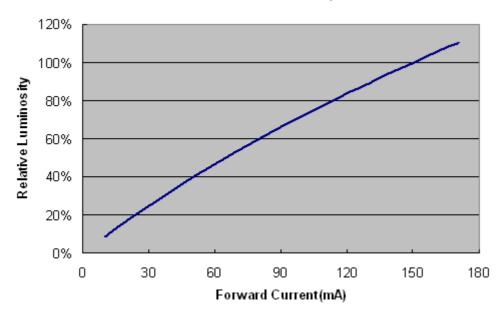




Forward Voltage vs. Forward Current

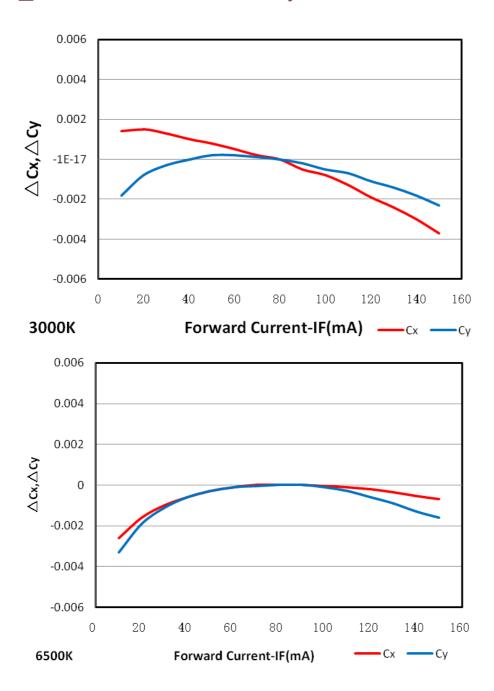


Forward Current vs. Relative Luminosity



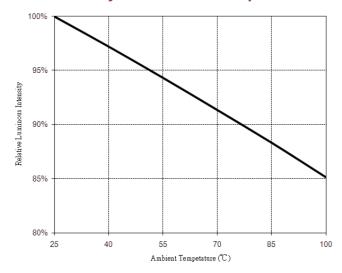


Forward Current vs. Chromaticity Coordinate

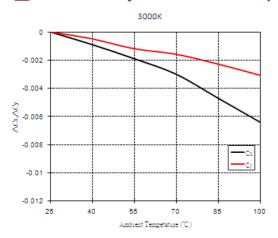


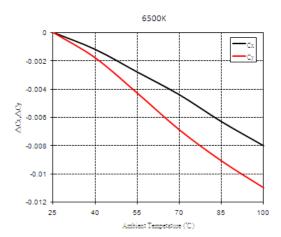


Relative Luminous Intensity vs. Ambient Temperature

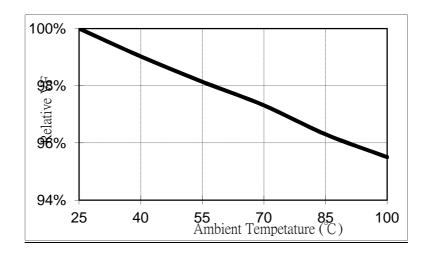


■ Chromaticity vs. Ambient Temperature





Relative VF vs. Ambient Temperature





Reliability

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Reliability test

ltem	Condition	Time/Cycle	
Steady State Operating Life of Low	40°C Operating	1000 Hrs	
Temperature -40°C	-40°C Operating	1000 HIS	
Steady State Operating Life of High	60°C Operating	1000 Hrs	
Temperature 60°C	60°C Operating	1000 Hrs	
Steady State Operating Life of High	Ts 105 °C Operating	1000 Hrs	
Temperature Ts105°C	is 105 c Operating		
Low temperature storage -40°C	-40°C Storage	1000 Hrs	
High temperature storage 100°C	100°C Storage	1000 Hrs	
Steady State Operating Life of High	60°C/00°/ Operating	1000 Hrs	
Humidity Heat 60°C90%	60°C/90% Operating	1000 HIS	
Resistance to soldering heat on PCB	pre-store@60°C, 60%RH for 52hrs	1 cycle	
(JEDEC MSL3)	Tsld max.=260°C 10sec	3 Times	
Thermal shock	-40°C/20minr ~5minr ~ 100°C/20min	100 Cycles	

Judgment Criteria

Item	Symbol	Test Condition	Judgment Criteria
Forward Voltage	Vf	150mA	ΔVf < 10 %
Luminous Flux	lv	150mA	ΔIv < 30 %



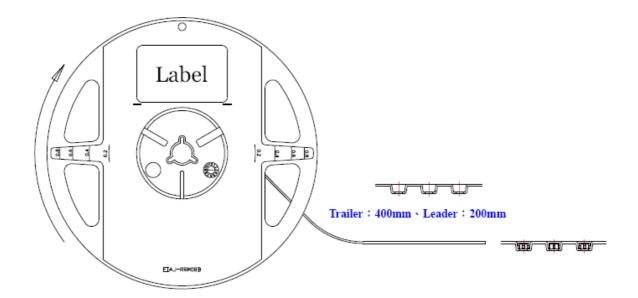
Packing

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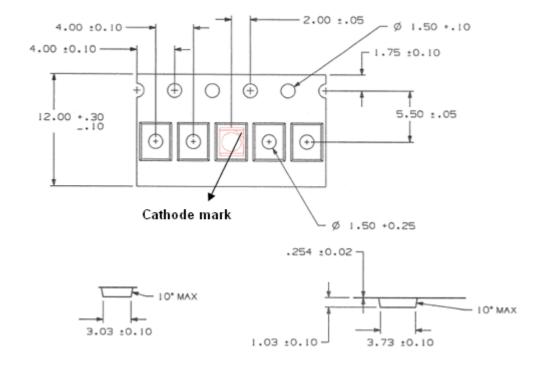
Label



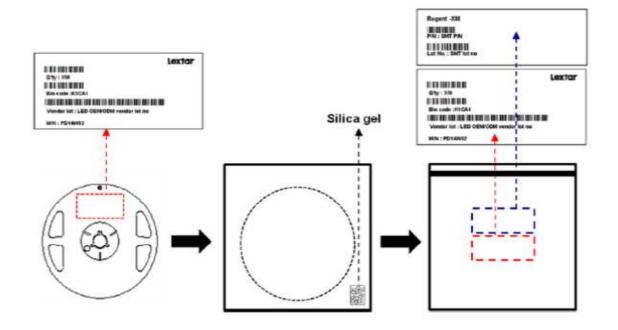
Carrier Taping







Shield Bag Taping

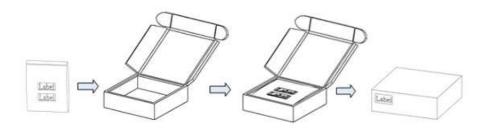




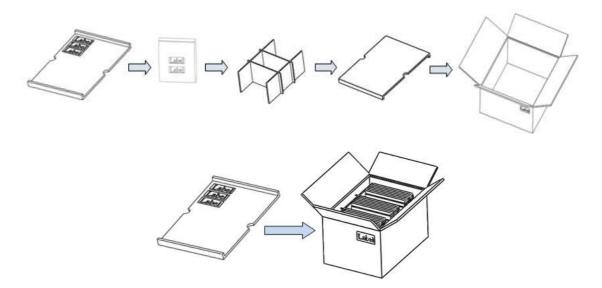
Packing Box

Туре	Large Box	x Medium Box		Large Box		\	Small Box	
Dimension	541X511X276r	mm	385X303X260ı	mm	283X235x70n	nm		
Maximum Reels	7"X12mm Reel	64/R	7"X12mm Reel	21/R	7"X12mm Reel	4/R		
Minimum Reels	7"X12mm Reel	32/R	7"X12mm Reel	9/R	7"X12mm Reel	1/R		

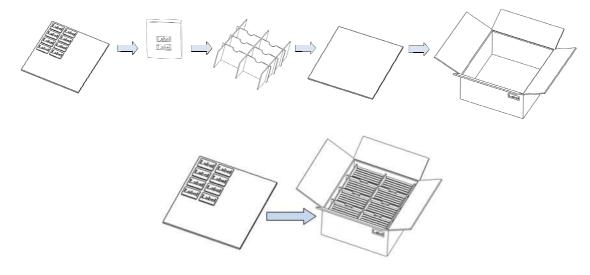
Small Box



■ Medium Box



Large Box





Precautions

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■Safety Precautions

- The LED light output is too strong for human eyes without shield. Prevent eye contact directly more than seconds.
- Ensure operating under maximum rating.

Storage

- Before opening the package, the LEDs should storage under 30℃, 60% RH.
- After opening the package bag, the LEDs should be keep under 30℃, 60% RH.
 Recommend to use within 168hrs. If unused LEDs remain, suggest to store into moisture proof bag or original package bag with moisture absorbent material such as silica gel.
 Reseal well is necessary.
- If the product exceeded the storage period or the moisture absorbent material faded away, baking treatment should be done by following conditions.
 Bake condition: 60°C, 12hours (One time only).

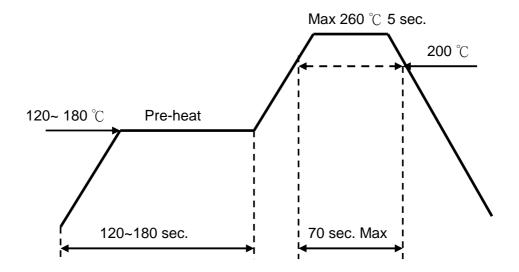
Soldering Notice and Conditions

- When soldering LEDs,
- Do not solder/reflow the same LED over two times.
- Recommend soldering conditions:

Reflow soldering: Pre-heat 180 °C max, 180 sec. max.

Peak 260 $^{\circ}$ C max , 5 sec. max.

Reflow temperature profile as below: (lead-free solder)





- When soldering, don't put stress on the LEDs
- After LEDs have been soldered, strongly recommend not to repair to keep the LEDs performance.

Static Electricity

- LED package is extremely sensitive to static electricity. It's recommended that
 anti-electrostatic glove and wrist band is necessary when handling the LEDs. All devices
 are also be grounded properly as well.
- Protection devices design should be considered in the LED driving circuit.

Cleaning

- If washing is required, recommend to use alcohol as a solvent.
- Recommend to avoid cleaning the LEDs by ultrasonic. If necessary, pre-test the LED is necessary to confirm whether any damage occur after the process.



Revision History

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Date	Contents	Writer	Approved
2014.12.22	New version	Rock Yen	Berris Huang
2015.02.12	5step CIE modify	Rock Yen	Berris Huang
2015.04.10	3step CIE modify	Rock Yen	Berris Huang
2015.10.13	Tolunce modify	Rock Yen	Berris Huang
2016.6.1	Reel size modification	Louis Chou	Berris Huang
2016.9.5	ERP binning updated	Louis Chou	Berris Huang

Smart Lighting Amazing Life

Lextar Electronics Corp. is the leading LED (Light Emitting Diode)

maker integrating upper stream epitaxial, middle stream chip, and downstream package,

SMT and LED lighting applications. Founded in May, 2008, Lextar is a subsidiary of AU Optronics,

the leading TFT-LCD and solar PV manufacturer. Lextar's product applications include lighting and LCD backlight.

Lextar's manufacturing sites include Hsinchu and Chunan in Taiwan, and Suzhou in China.

The company turnover in 2012 is 340 million USB: Corporation. All rights reserved. Lextar.com